

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	JIMMY CHEW	12/01/2019
RECEIVING PARTY DATA		
Name:	PEP INOVATION PTE. LTD.	
Street Address:	8 ADMIRALTY STREET	
Internal Address:	#01-07/10	
City:	SINGAPORE	
State/Country:	SINGAPORE	
Postal Code:	757438	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	16703877
CORRESPONDENCE DATA		
Fax Number:		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	(65)68549881	
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Correspondent Name:	DEXTER KAM CHIN	
Address Line 1:	7500A BEACH ROAD	
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ATTORNEY DOCKET NUMBER:	PEPP2019NAT83US0	
NAME OF SUBMITTER:	DEXTER KAM CHIN	
SIGNATURE:	/dexter chin/	
DATE SIGNED:	12/13/2019	
Total Attachments: 3		
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ASSIGNMENT

For good and valuable consideration, I, **Jimmy CHEW**, residing at 8 Admiralty Street #01-07/10 Singapore 757438, a citizen of the Republic of Singapore;

Hereby sell, assign, and transfer to **PEP INNOVATION PTE. LTD.**, a corporation of **Singapore**, having its principal place of business at 8 Admiralty Street #01-07/10 Singapore 757438,

hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently here within, and is entitled:

PACKAGING METHOD, PANEL ASSEMBLY, WAFER PACKAGE AND CHIP PACKAGE

and in and to said application and all divisional, continuing substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

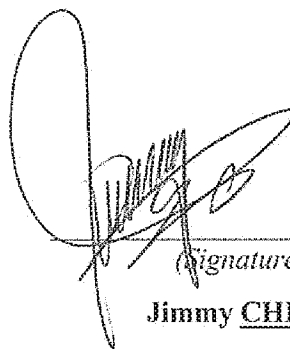
Agree that Assignee may apply for and receive Letters Patent for said improvements in its own name, and that, when requested, without charge to but at the expense of said Assignee, their successors, assigns, and legal representatives to carry out in good faith the intent and purpose of this agreement, the undersigned will execute all divisional, continuing substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible

which said Assignee, its successors, assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date:

1/12/2019



(Signature)

Jimmy CHEW

Witness 1:

Zheng Guoqin
(Signature)

ZHENG GUOQIN
(Print name)

Witness 2:

Lee Siew Wen
(Signature)

LEE SIEW WEN
(Print name)